

THERMAL RESISTANCE MAXIMUM RATINGS

| Parameter | Symbol | Max | Unit |
|---|---------------------|------|------|
| Junction-to-Case - Steady State (Note 1) | $R_{	ext{	heta}JC}$ | 1.01 | °C/W |
| Junction-to-Ambient - Steady State (Note 1) | $R_{\theta JA}$ | 40 | |

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

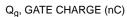
| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit |
|-----------------------------------|--------|---|-----|-----|-----|------|
| OFF CHARACTERISTICS | | | | | | |
| Droin to Course Breekdown Voltogo | V | $\lambda = 0 \lambda (1 - 1 m \Lambda)$ | 6E0 | | | V |

| Drain-to-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0 V, I_{D} = 1 mA$ | 650 | - | - | V | |
|--|--------------------------------------|--|-----|---|---|---|--|
| Drain-to-Source Breakdown Voltage Temperature Coefficient | V _{(BR)DSS} /T _J | $I_D = 20 \text{ mA}$, referenced to 25°C | | | | | |

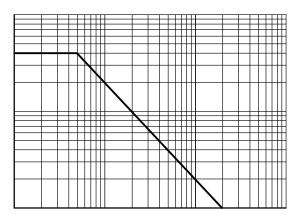
ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified) (continued)

| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit |
|----------------------------|------------------|---|-----|------|-----|------|
| DRAIN-SOURCE DIODE CHARACT | TERISTICS | | | | | |
| Reverse Recovery Time | t _{RR} | V _{GS} = -5/18 V, I _{SD} = 15 A, dI _S /dt = 1000 A/μs | - | 18 | - | ns |
| Reverse Recovery Charge | Q _{RR} | dI _S /dt = 1000 A/μs | - | 85 | - | nC |
| Reverse Recovery Energy | E _{REC} | | - | 10.6 | - | μJ |
| | | | - | - | - | - |
| | | | | | | |
| | | | | | | |

TYPICAL CHARACTERISTICS (CONTINUED)

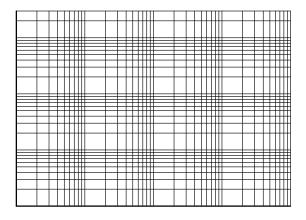


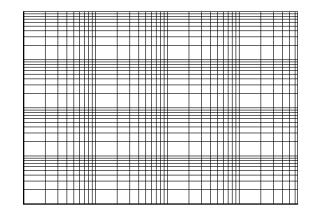


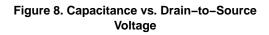


t_{AV}

Figure 9. Unclamped Inductive Switching Capability







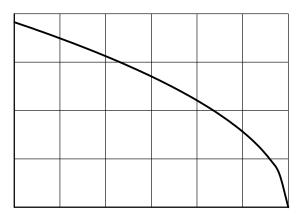
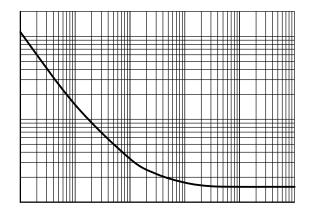


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

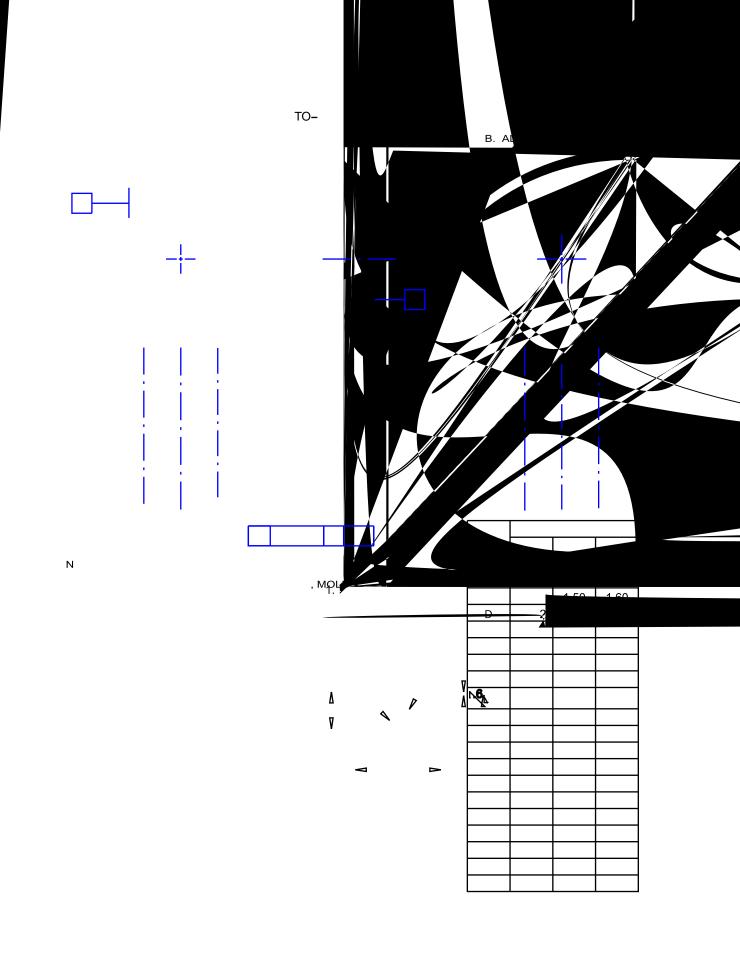


TYPICAL CHARACTERISTICS (CONTINUED)

| | | | | | | | | | | | _ | | | | _ | |
|--------------|-------------|--|-----|--|---|-------|-----|---|---|--|---|----|--|--|---|---|
| | | | | | | | | | | | | ++ | | | | + |
| 0.5 Duty Cyc | le 🗖 🗖 | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | |
| 0.2 | | | | | | | | | | | | | | | | |
| 0.1 | | | | | | | | | | | | | | | | |
| 0.05 | + + + + + + | | | | - | - ' ' | | 1 | I | | + | | | | _ | + |
| 0.00 | | | | | | | | | - | | | | | | | |
| | | | +++ | | | _ | | | | | + | ++ | | | | |
| 0.02 | | | | | | - P | ЪМ | | | | _ | | | | | |
| 0.02 | | | | | | | DIW | | | | | | | | | |
| | | | | | | _ | | | | | | | | | | |
| | 0.0 | | | | | _ | - | | | | T | | | | | |
| Single Puls | e | | | | | - | | | I | | T | | | | | |

t, RECTANGULAR PULSE DURATION (sec)

Figure 13. Junction-to-Case Thermal Response



onsemi, , and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or incruit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi